



# Product Change Notification

## 108389 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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# Product Change Notification

**Change Notification #:** 108389 - 00  
**Change Title:** CE5037 & CE5039, PCN 108389-00,  
Manufacturing Site, Qualification of  
Additional Assembly and Test Site  
**Date of Publication:** April 11, 2008

## Key Characteristics of the Change:

Manufacturing Site

## Forecasted Key Milestones:

<b>Date of Samples Availability:</b>	May 01, 2008
<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	Jul 10, 2008

## Description of Change to the Customer:

In order to ensure a continuous supply of Intel's CE5037 & CE5039, Intel will be qualifying an additional assembly and test site. The new site will be located in Shanghai, China. The attached list of materials specifies changes to indirect packaging materials.

## Customer Impact of Change and Recommended Action:

Intel does not anticipate any impact to the customer with this change. Customers should be ready to receive product from this as well as all other qualified existing assembly/test sites for these products.







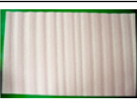

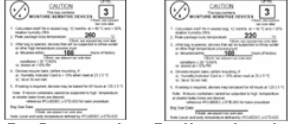

## Products Affected / Intel Ordering Codes:

Product Code	Affected S-Spec	Affected MM#
WGCE5037		882557
WGCE5037 S	S L9FV	882558
WGCE5039 S	S L9FW	882559
WGCE5039		882560











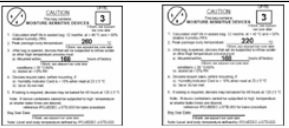
## Reference Documents / Attachments:

### Packing Material List

#### JEDEC Tray Dry-Pack

ASESH Standard Packing Material List For JEDEC Tray Desiccant Dry Packing						
Item	Supplier	ASESH PN	Specification	sample picture	Remark	
1	JEDEC Tray			NA	Follow customer's requirement	
2	Inner Box			NA	Follow customer's requirement	
3	Outer Box	DAXIN	2-OB-01-0000038	385*322*305mm		
4	Moisture Barrier Bag	MAKE ATP	2-AB-01-0000016 2-AB-01-0000014	500X255X0.178 mm		
5	Desiccant Pouch	NEFAB	2-DE-01-0000003	1/2 unit		
6	Humidity Indicator Card	Multisorb	2-HI-01-0000005	3 Spots 5%,10%,15%		
7	Sealing Tape	HUANQIU	9AA021225MFG0187	6.0*40码		
8	BLACK Poly Strapping	NEFAB	2-PP-01-0000003	Black, 9mm wide, 1KM/ROLL		
9	Bubble Wrap	FAGERDALA	2-FA-01-0000002	500X315X3 mm		
11	Bar Code Label	HENGYU	2-LB-01-0000002	110*55mm		Follow customer's requirement
12	Caution Label	HENGYU YUANGTAO	2-LB-01-0000103 2-LB-01-0000107	76.2mm*76.2mm, Level 3(for green) 76.2mm*76.2mm, Level 3(for normal)	 For Green product For Normal product	
13	Cardboard Sheet	DAXIN	2-OT-02-0000001	325*140*7.62 mm		

**Packing Material List**  
**TAPE and REEL Dry-Pack**

ASESH Standard Packing Material List For T/R Dry-Packing						
Item	Supplier	ASESH PN	Specification	sample picture	Remark	
1	Reel			NA	According to customer's requirement	
2	Carrier Tape			NA	According to customer's requirement	
3	Cover Tape			NA	According to customer's requirement	
4	Tape and Reel Box			NA	According to customer's requirement	
5	Outer Box	DAXIN	2-OB-01-0000035	370*360*260mm		
6	Moisture Barrier Bag	MAKE	2-AB-01-0000027	457*406*0.1524 mm		
7	Desiccant Pouch	WISEPAC	2-DE-01-0000008	2 Unit Clay		
8	Humidity Indicator Card	Multisorb	2-HI-01-0000005	3 Spots 5%,10%,15%		
9	Sealing Tape	HUANGUIU	9AA021225MFG0187	6.0*40mm		
10	Protective band			NA	According to customer's requirement	
11	ESD Label	HENGYU	2-LB-01-0000052	51*51mm		
12	Bubble Wrap	NEFAB	2-BB-01-0000005	310*310*5mm		
13	Foam	NEFAB	2-FA-01-0000012	44*44*30mm		
14	Bar Code Label for Box and MBB	NA	NA	NA		According to customer's requirement
15	Bar Code Label for Reel	NA	NA	NA		According to customer's requirement
16	Moisture Sensitive Label	HENGYU YUANGTAO	2-LB-01-0000103 2-LB-01-0000107	76.2mm*76.2mm, Level 3(for green) 76.2mm*76.2mm, Level 3(for normal)		For Green product For normal product

## **PCN Revision History:**

**Date of Revision:**

April 11, 2008

**Revision Number:**

00

**Reason:**

Originally Published PCN